

ABSTRACT OF THE DISCLOSURE

In manufacturing a multi-layer printed circuit board (PCB), different processes are employed for forming
5 inner and outer circuit layers of the PCB. Particularly, second and third inner circuit layers of the multi-layer PCB are formed with the resin build-up process through liquid epoxy coating or dry film type epoxy laminating to enable refinement of
10 circuits provided thereon, and two outer circuit layers of the multi-layer PCB are formed on copper clad and insulating dielectric with the lamination process to improve the thermal resistance, copper peel strength, structural stiffness, thermal stress
15 reliability, and size stability of the completed PCB. The multi-layer PCB manufactured with two different processes has improved quality and reliability, and may be manufactured at reduced cost.